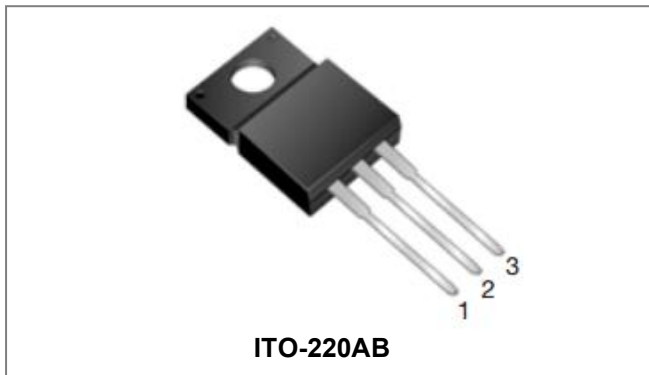


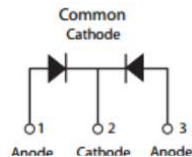
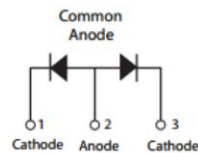
STF3060C(R) SCHOTTKY RECTIFIER



Features

- 150 °C T_J operation
- Ultralow forward voltage drop
- High purity, high temperature epoxy encapsulation for enhanced mechanical strength and moisture resistance
- High frequency operation
- Guard ring for enhanced ruggedness and long term reliability
- Trench MOS Schottky technology
- This is a Pb – Free Device
- All SMC parts are traceable to the wafer lot
- Additional testing can be offered upon request

Circuit Diagram


STF3060C

STF3060CR

Applications

- Switching power supply
- Converters
- Free-Wheeling diodes
- Reverse battery protection

Maximum Ratings:

Characteristics	Symbol	Condition	Max.	Units
Peak Repetitive Reverse Voltage	V _{RRM}	-	60	V
Working Peak Reverse Voltage	V _{RWM}			
DC Blocking Voltage	V _R			
Average Rectified Forward Current	I _{F(AV)}	50% duty cycle @T _c =100°C, rectangular wave form	15(Per Leg) 30(Per Device)	A
Peak One Cycle Non-Repetitive Surge Current(Per Leg)	I _{FSM}	8.3ms, Half Sine pulse, T _c =25°C	170	A

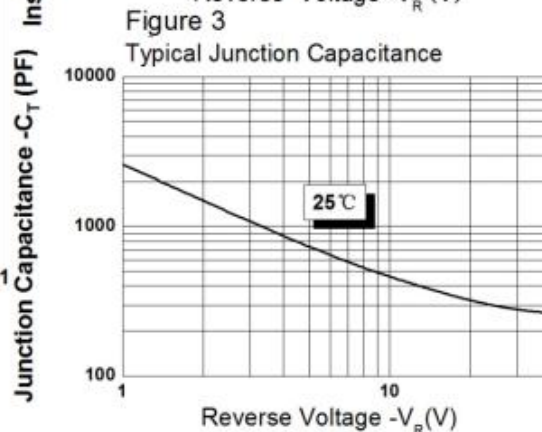
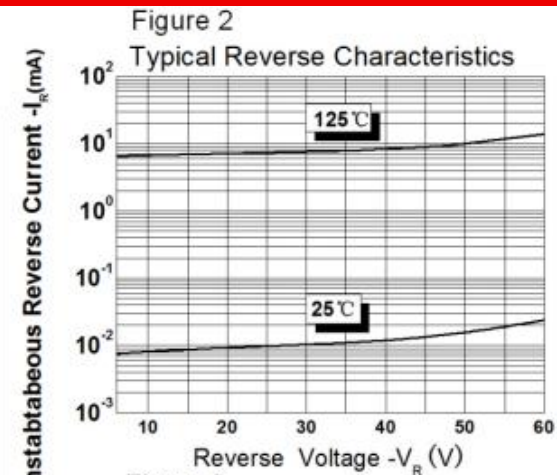
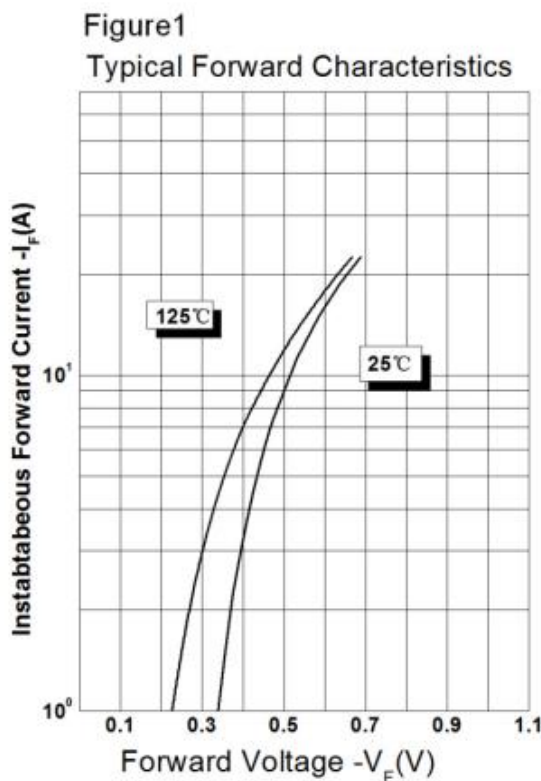
Thermal-Mechanical Specifications:

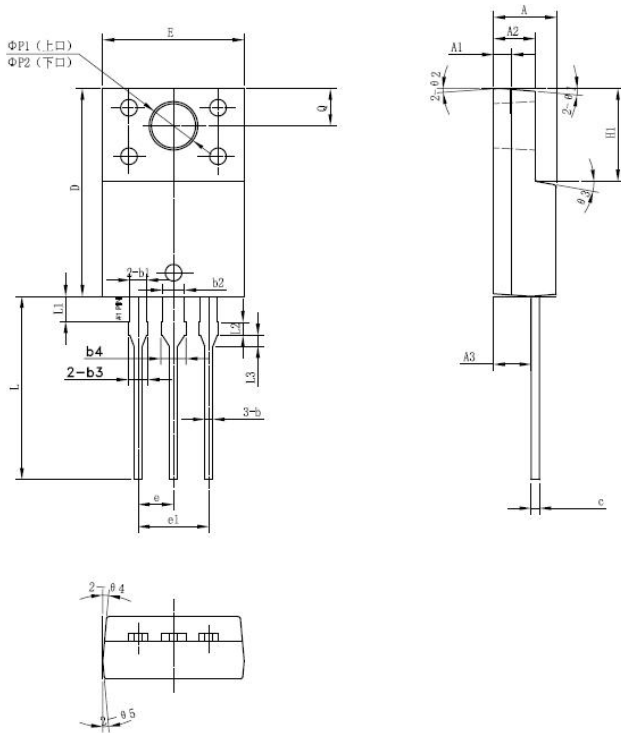
Characteristics	Symbol	Condition	Specification	Units
Junction Temperature	T _J	-	-55 to +150	°C
Storage Temperature	T _{stg}	-	-55 to +150	°C
Typical Thermal Resistance Junction to Case(Per Leg)	R _{θJC}	DC operation	6	°C/W
Approximate Weight	wt	-	2	g
Case Style		ITO-220AB		

Electrical Characteristics:

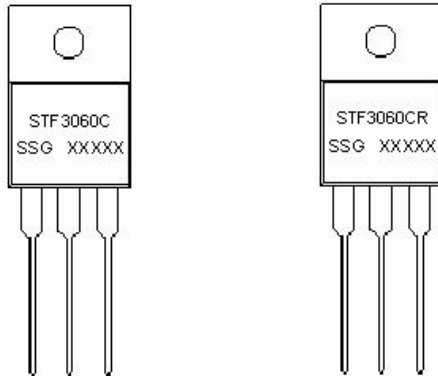
Characteristics	Symbol	Condition	Typ.	Max.	Units
Forward Voltage Drop(Per Leg)*	V_{F1}	@ 5A, Pulse, $T_J = 25^\circ\text{C}$	0.42	-	V
		@ 7.5A, Pulse, $T_J = 25^\circ\text{C}$	0.48	-	
@ 15A, Pulse, $T_J = 25^\circ\text{C}$	0.59	0.70			
	V_{F2}	@ 5A, Pulse, $T_J = 25^\circ\text{C}$	0.35	-	V
		@ 7.5A, Pulse, $T_J = 125^\circ\text{C}$	0.41	-	
		@ 15A, Pulse, $T_J = 125^\circ\text{C}$	0.55	0.65	
Reverse Current(Per Leg)*	I_{R1}	@ $V_R = \text{rated } V_R, T_J = 25^\circ\text{C}$	0.03	1.2	mA
	I_{R2}	@ $V_R = \text{rated } V_R, T_J = 125^\circ\text{C}$	14	45	mA
Junction Capacitance	C_T	@ $V_R = 5\text{V}, T_C = 25^\circ\text{C}$ $f_{\text{SIG}} = 1\text{MHz}$	712	-	pF
RSM Isolation Voltage ($t = 1.0$ second, R. H. $< 30\%$, $T_A = 25^\circ\text{C}$)	V_{ISO}	Clip mounting, the epoxy body away from the heatsink edge by more than 0.110" along the lead direction.	-	4500	V
		Clip mounting, the epoxy body is inside the heatsink.	-	3500	
		Screw mounting, the epoxy body is inside the heatsink.	-	1500	

* Pulse width $< 300 \mu\text{s}$, duty cycle $< 2\%$

Ratings and Characteristics Curves


Mechanical Dimensions ITO-220AB


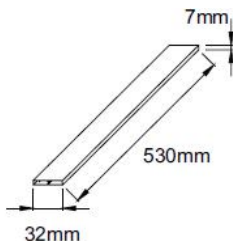
SYMBOL	Millimeters		
	MIN.	TYP.	MAX.
A	4.30	4.50	4.70
A1	1.10	1.30	1.50
A2	2.80	3.00	3.20
A3	2.50	2.70	2.90
b	0.50	0.60	0.75
b1	1.10	1.20	1.35
b2	1.50	1.60	1.75
b3	1.20	1.30	1.45
b4	1.60	1.70	1.85
c	0.50	0.60	0.75
D	14.80	15.00	15.20
E	9.96	10.16	10.36
e		2.55	
e1		5.10	
H1	6.50	6.70	6.90
L	12.70	13.20	13.70
L1	1.60	1.80	2.00
L2	0.80	1.00	1.20
L3	0.60	0.80	1.00
ΦP1(上口)	3.30	3.50	3.70
ΦP2(下口)	2.99	3.19	3.39
Q	2.50	2.70	2.90
Θ1		5°	
Θ2		4°	
Θ3		10°	
Θ4		5°	
Θ5		5°	

Marking Diagram


Where XXXXX is YYWWL

- ST = Device Type
- F = Package type
- 30 = Forward Current (30A)
- 60 = Reverse Voltage (60V)
- C(R) = Configuration
- SSG = SSG
- YY = Year
- WW = Week
- L = Lot Number

Cautions: Molding resin
 Epoxy resin UL:94V-0

Tube Specification

Ordering Information

Device	Package	Shipping
STF3060C(R)	ITO-220AB (Pb-Free)	50 pcs/ tube

For information on tape and reel specifications, including part orientation and tape sizes, please refer to our tape and reel packaging specification.

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